

Trade Name: SRC HM1 RMA (Ag2) V16L 12%

- 1. Company Address:
 Almit GmbH
 Ph.: +49 6066 96884-0

 Dekan-Groh-Straße 4
 Fax: +49 6066 96884-18

 (DE) 64720 Michelstadt near Frankfurt

3. Diameter & Allowance:

Weight	20g	40g	80g	100g	250g
Allowance			-0, +5g		

4. Deliverable Reel Size:

Metal Name	Solidus °C	Liquidus °C	Specific Gravity
Sn62 AG2	179	190	8.4

5. Physical Properties:

Test	Characteristics	Test Methods
Metal Content	88.0 ± 1.0	IPC-TM-650 2.2.20
Silver Chromate	pass	IPC-TM-650 2.3.33
Copper Mirror Test	pass	IPC-TM-650 2.3.32
SIR (85°C, 85%, 168hr) (Ω)	≥ 1x10 ⁸	IPC-TM-650 2.6.3.3
Corrosion Test	pass	IPC-TM-650 2.6.15
Flux materials composition	RO	J-STD 004 1.2
Quantitative Halide	L1 < 0.5%	IPC-TM-650 2.3.35
Fluorides By Spot Test	pass	IPC-TM-650 2.6.35.1

6. Characterisitcs:

Composition	Components							
composition	Sn	Pb	Cu	Ag	Sb	Bi	Au	In
Standard	62.0	Rest	≤0.05	2.0	≤0.12	≤0.1	≤0.08	≤0.1
Composition	Components							
Composition	A	AI	As	Cd	Fe	Ni	Zn	
Standard	≤0.	001	≤0.03	≤0.002	≤0.02	≤0.01	≤0.001	

7. Solder Powder Size & Distribuon :

% of Sample by Weight – Nominal Size

Туре		notless than 1%at least 80%larger thanlarger thanbetween		at most 10% less than	
Type 4	V16L	40 Microns	38 Microns	20 - 38 Microns	20 Microns

8. Lot-Size: A single lot contains 500kg which is the amount of one melting.

9. Quality and Inspecon :

Inspecon items are applied to each lot as follows :

Test No.	Inspection Item	Contents	Standard	
1	Appearance	Color	Comparison with Limit Specime	
2	Weight	Net Weight	-0 ; +5	(g)
3	Solder Powder Size	20 - 38 µm V16L	94 ≤	(wt%)
		Pb	Rest	(wt%)
4	Motal Composition	Sn	62.0 ± 0.5	(wt%)
4	4 Metal Composition	Ag	2.0 ± 0.2	(wt%)
			0	(wt%)
5		Flux Content	12.0 ± 0.5	(wt%)
6		Solder Balling Test	Comparison with Limit Specim	
7	Characteristics	Viscosity (Spiral type, 10rpm, 25°C) (IPC-650-2.4.34.3)	80000 ± 30000 80 ± 30	(cps) (Pa•s)
8		Solderability on Cu-Plate	Comparison with Limit Specim	
9		Dryness	Chalk powder s removed from ea	hould be easily ch test specimen.

*Straight lines of solder paste are printed on a JIS-2 type substrate then reflowed. The reflowed solder is examined with a stereo microscope at 30X magnification. No more than 2 solder balls larger than one fifth the size of the pattern gap is allowed per gap.

10. Packing:

Ŭ Ū	Individual Package	Outer Package		
			V	
Unit	Packing	Unit	Packing	
20g	5cc Catridge	-		
40g	10cc Catridge	-		
80g	30cc Catridge	-	Cardboard Box	
100g	30cc Catridge	-		
250g	100cc Catridge	-		

11. Identification:

	Catridge	Cardboard
Name	Almit-Solder-Paste SRC HM1 RMA (Ag2) V16L 12%	same as the left
Lot Nr.	(Ex.) 120119-9	dto.
Solder Powder Size	20 - 38 µm	dto.
Date of Mfg.	(Ex.) 19.01.2012	dto.
Net Weight	(Ex.) 20g	dto.
Maker	Nihon Almit Co. Ltd.	dto.

10. Maker Address:Nihon Almit Co. Ltd.Almit Bldg., 2-14-2 Yayoicho, Nakano-ku, Tokyo, Japan

- In case of changing this specification it should be accepted by:

 Signature______
 Date______
- **12.** This product is manufactured, using all guaranteed materials according to the legal law regulations.

13. Shelf Life:

Up to

6 month from the manufactured date (lot number).